

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIA-CHUNG CHEN</td> <td>10/17/2013</td> </tr> <tr> <td>FU-HUAN TSAI</td> <td>10/17/2013</td> </tr> <tr> <td>FENG YUAN</td> <td>10/17/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHIA-CHUNG CHEN	10/17/2013	FU-HUAN TSAI	10/17/2013	FENG YUAN	10/17/2013				
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. VI</td> </tr> <tr> <td>Internal Address:</td> <td>HSINCHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8, LI-HSIN RD. VI	Internal Address:	HSINCHU SCIENCE PARK	City:	HSINCHU	State/Country:	TAIWAN	Postal Code:	300
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CORRESPONDENCE DATA													
<p>Fax Number:</p> <p>Phone: 7036841111</p> <p>Email: tsmc@ipfirm.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: LOWE HAUPTMAN & HAM, LLP (TSMC)</p> <p>Address Line 1: 2318 MILL ROAD</p> <p>Address Line 2: SUITE 1400</p> <p>Address Line 4: ALEXANDRIA, VIRGINIA 22314</p>													
ATTORNEY DOCKET NUMBER:	T5057-962												
NAME OF SUBMITTER:	RANDY A. NORANBROCK												

Signature:	/Randy A. Noranbrock/
Date:	10/23/2013
Total Attachments: 1 source=EfiledAssgn#page1.tif	

Docket No. T5057-962
TSMC2013-1118

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Chia-Chung CHEN 3) Feng YUAN
2) Fu-Huan TSAI

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled.

FINFET HAVING ISOLATION STRUCTURE AND METHOD OF FORMING THE SAME

(a) for which an application for United States Letters Patent was filed on October 23, 2013, and identified by United States Patent Application No. 14/060,784; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chia-Chung Chen
Name: Chia-Chung CHEN

10/17, 2013
Date:

2) Fu-Huan Tsai
Name: Fu-Huan TSAI

10/17, 2013
Date:

2) Feng Yuan
Name: Feng YUAN

10/17, 2013
Date: